


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/23/14159	
1.3 Title of PCI	ST MUAR (Malaysia) LQFP14x14 package leadframe enhancement for STM32F4xx listed products	
1.4 Product Category	STM32F413VGTx STM32F413VHT6 STM32F423VHT6	
1.5 Issue date	2023-07-04	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	ST MUAR (Malaysia)

4. Description of change

	Old	New
4.1 Description	Leadframe without Lead Lock Tape	Leadframe with Lead Lock Tape (LLT)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	New state of the art technic
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	tracability ensure by ST internal tool
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7. Timing / schedule

7.1 Date of qualification results	2023-05-24
7.2 Intended start of delivery	2023-08-16
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	14159 MDG-MCD-RER2022 V2.0 - PCI12541 PCI14159 - ST Muar (Malaysia) LQFP14x14 package leadframe enhancement.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-07-04

9. Attachments (additional documentations)

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F413VGT3	
	STM32F413VGT6	
	STM32F423VHT6	

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